

Abstract of the Disclosure

The method for removing particles that adhere to the surface of semiconductor wafers is constituted so as to sequentially carry out a first cleaning process in which semiconductor wafers 100 are cleaned for a prescribed time in cleaning tank 104 containing a first cleaning solution consisting of ozone water, and, after said first cleaning process, a second cleaning process in which said semiconductor wafers 100 are cleaned for a prescribed time in cleaning tank 106 containing a second cleaning solution consisting of hydrogen water.